

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of the Claims:

1. (Currently Amended) A device enclosure comprising:

a chassis including a top wall and an opposing bottom wall; and

a thermo-siphon device formed as an integral part of the top wall of the chassis,
the thermo-siphon device including ~~first heat pipe and a second heat pipe, a~~
~~vaporizing end of the first and second heat pipe coupled to a first metal plate,~~
and a condensing end of the first heat pipe coupled to a second metal plate, the
top wall partially encloses the thermo-siphon device, and a condensing end of the
~~second heat pipe coupled to a third metal plate.~~

2. (Currently Amended) The device enclosure of claim 1, wherein the
device is an electronic device.

3. (Currently Amended) The device enclosure of claim 2, wherein the
device enclosure is a computer chassis.

4. (Currently Amended) The device enclosure of claim 1, wherein the device is a non-electronic device.
5. (Cancelled).
6. (Cancelled).
7. (Cancelled).
8. (Cancelled).
9. (Currently Amended) The device enclosure of claim 1, wherein the top wall is fabricated from a metallic material.
10. (Currently Amended) The device enclosure of claim 1, wherein the thermo-siphon device is embedded in a cavity of the wall.
11. (Currently Amended) The device enclosure of claim 10, wherein the cavity is created during a fabrication process of the wall.
12. ~~(Canceled) The device of claim 1, wherein the wall partially encloses the thermo-siphon device.~~

13. (Currently Amended) The device enclosure of claim 12, wherein a portion of the thermo-siphon device is exposed to an interior of the enclosure.
14. (Currently Amended) The device enclosure of claim 12, wherein a portion of the thermo-siphon device is exposed to a heat sink.
15. (Cancelled).
16. (Cancelled).
17. (Currently Amended) The device enclosure of claim 1, wherein the thermo-siphon device is secured to a wall cavity through the means selected from the group consisting of a support provided by cavity walls, a thermal epoxy, and an interference fit with the wall cavity.
18. (Cancelled).
19. (Currently Amended) A system comprising:
 - a chassis including a top wall and an opposing wall; and
 - a thermo-siphon device formed as an integral part of the top wall of the chassis,
 - the thermo-siphon device including ~~first heat pipe and a second heat pipe, a~~

~~vaporizing end of the first and second heat pipe coupled to a first metal plate,
and a condensing end of the first heat pipe coupled to a second metal plate, and
a condensing end of the second heat pipe coupled to a third metal plate, the top
wall partially encloses the thermo-siphon device.~~

20. (Cancelled).

21. (Cancelled).

22. (Original) The system of claim 19, wherein the chassis is a computer chassis.

24. (Currently Presented) A computer chassis comprising:
a chassis including a top wall and an opposing wall; and
a thermo-siphon device formed as an integral part of wall of the chassis,
the thermo-siphon device including ~~first heat pipe and a second heat pipe, a
vaporizing end of the first and second heat pipe coupled to a first metal plate,
and a condensing end of the first heat pipe coupled to a second metal plate, the
top wall partially encloses the thermo-siphon device and a condensing end of
the second heat pipe coupled to a third metal plate.~~

25. (Original) The computer chassis of claim 24, wherein the thermo-siphon device is a heat pipe.

26. (Original) The computer chassis of claim 24, wherein the computer chassis is a notebook computer base.

27. (Cancelled).

28. ~~(Canceled) The computer chassis of claim 24, wherein the thermo-siphon device is embedded in the wall during the manufacturing process of the skin.~~